



100% Material Declaration Data Sheet FG900 Spartan-6

PK471 (v1.0) Jul 29, 2011

Average Weight: 4.054 g

| Component | Substance Description | CAS# or Description | % of Component | Use in Product | Component Weight/ Substance Weight (in grams) | Component % of Total |
|----------------------------|-----------------------|--|----------------|----------------|---|-------------------------|
| Silicon Die | | | | | 0.090946 | 2.243 |
| | Silicon | 7440-21-3 | 100.00 | Main material | 0.090946 | |
| Die Attach Material | | | | | 0.016016 | 0.395 |
| | Silver | 7440-22-4 | 77.50 | Main material | 0.012412 | |
| | Bismaleimide monomer | Trade Secret | 15.00 | Main material | 0.002402 | |
| | Acrylate monomer | Trade Secret | 7.50 | Main material | 0.001201 | |
| Mold Compound | | | | | 1.876994 | 46.302 |
| | Solid Epoxy Resin | Trade Secret | 5.00 | Main material | 0.093850 | |
| | Phenol Resin | Trade Secret | 5.00 | Main material | 0.093850 | |
| | Fused Silica | 60676-86-0 | 87.45 | Main material | 1.641431 | |
| | Metal Hydroxide | Trade Secret | 2.00 | Main material | 0.037540 | |
| | Carbon Black | 1333-86-4 | 0.55 | Main material | 0.010323 | |
| Gold Wire | | | | | 0.023056 | 0.569 |
| | Gold | 7440-57-5 | 99.05 | Main material | 0.022837 | |
| | Palladium | 7440-05-3 | 0.95 | Main material | 0.000219 | |
| Solder Balls | | | | | 0.856617 | 21.131 |
| | Tin (Sn) | 7440-31-5 | 63.00 | Main material | 0.539669 | |
| | Lead (Pb) | 7439-92-1 | 37.00 | Main material | 0.316948 | |
| Substrate | | | | | 1.190159 | 29.359 |
| | Copper | 7440-50-8 | 28.19 | Main material | 0.335483 | |
| | Nickel | 7440-02-0 | 4.13 | Main material | 0.049192 | |
| | Gold | 7440-57-5 | 0.30 | Main material | 0.003529 | |
| | BT (core) | 21645-51-2 7440-50-8 Epoxy resin | 59.49 | Main material | 0.708012 | |
| | Solder mask | 14807-96-6 7727-43-7 7631-86-9 34590-94-8 85954-11-6 | 7.89 | Main material | 0.093943 | |

Revision History

The following table shows the revision history for this document.

| Date | Version | Description of Revisions |
|----------|---------|--------------------------|
| 07/29/11 | 1.0 | Initial Xilinx release. |

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